

WHAT IS CLAIMED IS:

1. A preparation method for inductance element, comprising the following steps:
 prepare a substrate;
 prepare at least one coil on said substrate; said at least one coil having an external side;
 5 prepare a conductive material to connect the external side of said at least on coil to
 function as an plating electrode; and
 form a multileveled multiple-layered magnetic structure on said at least one coil.
 wherein material for said multiple-layered magnetic structure comprises a soft
 magnetic material; and
 10 wherein said multileveled magnetic structure is prepared through intermittent plating.
2. The method according to claim 1 wherein said at least one coil is a winded
 enameled wire coil, a planar coil or a coil formed on a printed circuit board
3. The method according to claim 1, wherein said conductive material is metalized
 such that said multiple-layered magnetic structure may be developed on said at least one coil.
- 15 4. The method according to claim 1 wherein said soft magnetic material comprises a
 21% Permalloy alloy or a super Permalloy.
5. An inductance element prepared according to anyone of claims 1-4.

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